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November 20, 2007

# DS91D180/DS91C180 100 MHz M-LVDS Line Driver/Receiver Pair

#### **General Description**

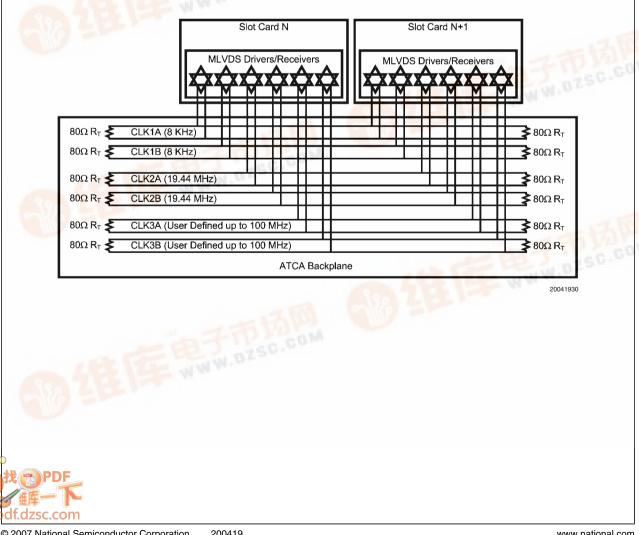
The DS91D180 and DS91C180 are 100 MHz M-LVDS (Multipoint Low Voltage Differential Signaling) line driver/receiver pairs designed for applications that utilize multipoint networks (e.g. clock distribution in ATCA and uTCA based systems). M-LVDS is a new bus interface standard (TIA/EIA-899) optimized for multidrop networks. Controlled edge rates, tight input receiver tresholds and increased drive strength are one of the key enhencments that make M-LVDS devices an ideal choice for distributing signals via multipoint networks.

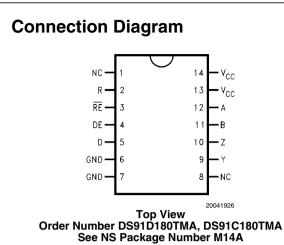
The DS91D180/DS91C180 driver input accepts LVTTL/LVC-MOS signals and converts them to differential M-LVDS signal levels. The DS91D180/DS91C180 receiver accepts low voltage differential signals (LVDS, B-LVDS, M-LVDS, LV-PECL and CML) and converts them to 3V LVCMOS signals. The DS91D180 device has a M-LVDS type 1 receiver input with no offset.The DS91C180 device has a type 2 receiver input which enable failsafe functionality.

#### Features

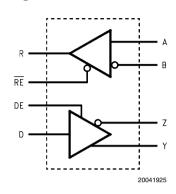
- DC to 100+ MHz / 200+ Mbps low power, low EMI operation
- Optimal for ATCA, uTCA clock distribution networks
- Meets or exceeds TIA/EIA-899 M-LVDS Standard
- Wide Input Common Mode Voltage for Increased Noise Immunity
- DS91D180 has type 1 receiver input
- DS91C180 has type 2 receiver input for fail-safe functionality
- Industrial temperature range
- Space saving SOIC-14 package (JEDEC MS-012)

# **Typical Application in an ATCA Clock Distribution Network**





#### Logic Diagram



Order Number	<b>Receiver Input</b>	Function	Package Type
DS91D180TMA	type 1	Data (0V threshold receiver)	SOIC/M14A
DS91C180TMA	type 2	Control (offset fail-safe receiver)	SOIC/M14A

#### **M-LVDS Receiver Types**

**Ordering Information** 

The EIA/TIA-899 M-LVDS standard specifies two different types of receiver input stages. A type 1 receiver has a conventional threshold that is centered at the midpoint of the input amplitude,  $V_{ID}/2$ . A type 2 receiver has a built in offset that is 100mV greater then  $V_{ID}/2$ . The type 2 receiver offset acts as a failsafe circuit where open or short circuits at the input will always result in the output stage being driven to a low logic state.

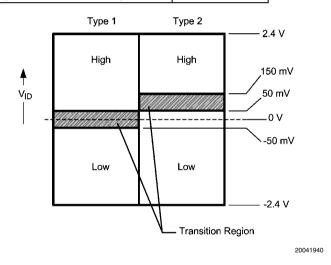


FIGURE 1. M-LVDS Receiver Input Thresholds

#### Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage, V <sub>CC</sub>	-0.3V to +4V
Control Input Voltages	-0.3V to (V <sub>CC</sub> + 0.3V)
Driver Input Voltage	-0.3V to (V <sub>CC</sub> + 0.3V)
Driver Output Voltages	-1.8V to +4.1V
Receiver Input Voltages	-1.8V to +4.1V
Receiver Output Voltage	-0.3V to (V <sub>CC</sub> + 0.3V)
Maximum Package Power Dissipa	tion at +25°C
SOIC Package	1.1 W
Derate SOIC Package	8.8mW/°C above +25°C
Thermal Resistance	
θ <sub>JA</sub>	113.7 °C/W
$\theta_{JC}$	36.9 °C/W
Maximum Junction Temperature	150°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature	
(Soldering, 4 seconds)	260°C

ESD Ratings:	
(HBM 1.5kΩ, 100pF)	≥ 5 kV
(EIAJ 0Ω, 200pF)	≥ 250 V
(CDM 0Ω, 0pF)	≥ 1000 V

# Recommended Operating Conditions

	Min	Тур	Мах	Units
Supply Voltage, V <sub>CC</sub>	3.0	3.3	3.6	V
Voltage at Any Bus Terminal	-1.4		+3.8	V
(Separate or Common-Mode)				
Differential Input Voltage V <sub>ID</sub>			2.4	V
High Level Input Voltage V <sub>IH</sub>	2.0		$V_{CC}$	V
Low Level Input Voltage V <sub>IL</sub>	0		0.8	V
Operating Free Air				
Temperature T <sub>A</sub>	-40	+25	+85	°C

## **Electrical Characteristics**

Over recommended operating supply and temperature ranges unless otherwise specified. (Notes 2, 3, 4, 8)

Symbol	ol Parameter Conditions			Min	Тур	Max	Unite
/I-LVDS D	river						
V <sub>YZ</sub> I	Differential output voltage magnitude	$R_L = 50\Omega, C_L = 5pF$		480		650	mV
ΔV <sub>YZ</sub>	Change in differential output voltage magnitude between logic states	Figure 2 and Figure 4		-50	0	+50	mV
/ <sub>OS(SS)</sub>	Steady-state common-mode output voltage	$R_L = 50\Omega, C_L = 5pF$		0.3	1.8	2.1	V
$\Delta V_{OS(SS)}$ I	Change in steady-state common-mode output voltage between logic states	Figure 2 and Figure 3		0		+50	mV
/ <sub>OS(PP)</sub>	Peak-to-peak common-mode output voltage	(V <sub>OS(pp)</sub> @ 500KHz clock)			143		mV
/ <sub>Y(OC)</sub>	Maximum steady-state open-circuit output voltage	Figure 5		0		2.4	V
/ <sub>Z(OC)</sub>	Maximum steady-state open-circuit output voltage			0		2.4	V
/ <sub>P(H)</sub>	Voltage overshoot, low-to-high level output	$R_{L} = 50\Omega, C_{L} = 5pF,$				$1.2V_{SS}$	V
P(L)	Voltage overshoot, high-to-low level output	C <sub>D</sub> = 0.5pF <i>Figure 7</i> and <i>Figure 8</i> (Note 9)		-0.2V <sub>S</sub>			v
IH	High-level input current (LVTTL inputs)	V <sub>IH</sub> = 2.0V		-15		15	μA
IL	Low-level input current (LVTTL inputs)	$V_{IL} = 0.8V$		-15		15	μA
/ <sub>IKL</sub>	Input Clamp Voltage (LVTTL inputs)	l <sub>IN</sub> = -18 mA		-1.5			V
OS	Differential short-circuit output current	Figure 6		-43		43	mA
/I-LVDS R	eceiver						
/ <sub>IT+</sub>	Positive-going differential input voltage threshold	See Function Tables	Type 1		20	50	mV
			Type 2		94	150	mV
/ <sub>IT-</sub>	Negative-going differential input voltage threshold	See Function Tables	Type 1	-50	20		mV
			Type 2	50	94		mV
он	High-level output voltage	I <sub>OH</sub> = -8mA		2.4	2.7		V
/ <sub>OL</sub>	Low-level output voltage	I <sub>OL</sub> = 8mA			0.28	0.4	V
oz	TRI-STATE output current	V <sub>O</sub> = 0V or 3.6V		-10		10	μA
OSR	Short circuit Rrceiver output current (LVTTL Output)	$V_0 = 0V$		-90	-48		mA

Symbol	Parameter	Conditions	Min	Тур	Max	Units
M-LVDS B	Bus (Input and Output) Pins					
I <sub>A</sub> , I <sub>Y</sub>	Receiver input or driver high-impedance output current	$V_{A,Y} = 3.8V, V_{B,Z} = 1.2V,$ DE = GND			32	μA
		V <sub>A,Y</sub> = 0V or 2.4V, V <sub>B,Z</sub> = 1.2V, DE = GND	-20		+20	μA
		$V_{A,Y} = -1.4V, V_{B,Z} = 1.2V,$ DE = GND	-32			μA
I <sub>B</sub> , I <sub>Z</sub>	Receiver input or driver high-impedance output current	$V_{B,Z} = 3.8V, V_{A,Y} = 1.2V,$ DE = GND			32	μA
		$V_{B,Z} = 0V \text{ or } 2.4V, V_{A,Y} = 1.2V, DE = GND$	-20		+20	μA
		$V_{B,Z} = -1.4V, V_{A,Y} = 1.2V,$ DE = GND	-32			μΑ
I <sub>AB</sub> , I <sub>YZ</sub>	Receiver input or driver high-impedance output differential current $(I_A - I_B \text{ or } I_Y - I_Z)$	$V_{A,Y} = V_{B,Z}$ , -1.4V $\leq V \leq 3.8V$ , DE = GND	-4		+4	μA
I <sub>A(OFF)</sub> , I <sub>Y(OFF)</sub>	Receiver input or driver high-impedance output power-off current	$V_{A,Y} = 3.8V, V_{B,Z} = 1.2V,$ $DE = V_{CC} = 1.5V$			32	μA
		$V_{A,Y} = 0V \text{ or } 2.4V, V_{B,Z} = 1.2V,$ DE = $V_{CC} = 1.5V$	-20		+20	μA
		$V_{A,Y} = -1.4V, V_{B,Z} = 1.2V,$ DE = V <sub>CC</sub> = 1.5V	-32			μA
I <sub>B(OFF)</sub> , I <sub>Z(OFF)</sub>	Receiver input or driver high-impedance output power-off current	$V_{B,Z} = 3.8V, V_{A,Y} = 1.2V,$ $DE = V_{CC} = 1.5V$			32	μA
		$V_{B,Z} = 0V \text{ or } 2.4V, V_{A,Y} = 1.2V,$ DE = $V_{CC} = 1.5V$	-20		+20	μA
		$V_{B,Z} = -1.4V, V_{A,Y} = 1.2V,$ DE = V <sub>CC</sub> = 1.5V	-32			μA
I <sub>AB(OFF)</sub> , I <sub>YZ(OFF)</sub>	Receiver input or driver high-impedance output power-off differential current $(I_{A(OFF)} - I_{B(OFF)} \text{ or } I_{Y(OFF)} - I_{Z(OFF)})$	$V_{A,Y} = V_{B,Z}, -1.4V \le V \le 3.8V,$ $V_{CC} = 1.5V, DE = 1.5V$	-4		+4	μA
C <sub>A</sub> , C <sub>B</sub>	Receiver input capacitance	V <sub>CC</sub> = OPEN		5.1		pF
C <sub>Y</sub> , C <sub>Z</sub>	Driver output capacitance			8.5		pF
C <sub>AB</sub>	Receiver input differential capacitance			2.5		pF
C <sub>YZ</sub>	Driver output differential capacitance			5.5		pF
C <sub>A/B</sub> , C <sub>Y/Z</sub>	Receiver input or driver output capacitance balance $(C_A/C_B \text{ or } C_Y/C_Z)$			1.0		
	CURRENT (V <sub>cc</sub> )					
I <sub>CCD</sub>	Driver Supply Current	$R_L = 50\Omega$ , $DE = V_{CC}$ , $\overline{RE} = V_{CC}$		17	29.5	mA
I <sub>CCZ</sub>	TRI-STATE Supply Current	$\overline{DE} = GND, \overline{RE} = V_{CC}$		7	9.0	mA
	Receiver Supply Current	$DE = GND, \overline{RE} = GND$		14	18.5	mA
I <sub>CCB</sub>	Supply Current, Driver and Receiver Enabled	DE = V <sub>CC</sub> , <del>RE</del> = GND		20	29.5	mA

Switching Characteristics										
Over recommended operating supply and temperature ranges unless otherwise specified. (Notes 3, 8)										
Symbol	Parameter	Conditions	Min	Тур	Max	Units				
DRIVER AC S	DRIVER AC SPECIFICATION									
t <sub>PLH</sub>	Differential Propagation Delay Low to High	$R_{L} = 50\Omega, C_{L} = 5 \text{ pF},$	1.0	3.4	5.5	ns				
t <sub>PHL</sub>	Differential Propagation Delay High to Low	C <sub>D</sub> = 0.5 pF	1.0	3.1	5.5	ns				
t <sub>SKD1</sub> (t <sub>sk(p)</sub> )	Pulse Skew $ t_{PLHD} - t_{PHLD} $ (Notes 5, 9)	Figure 7 and Figure 8		300	420	ps				
t <sub>SKD3</sub>	Part-to-Part Skew (Notes 6, 9)				1.9	ns				
t <sub>TLH</sub> (t <sub>r</sub> )	Rise Time (Note 9)		1.0	1.8	3.0	ns				
t <sub>THL</sub> (t <sub>f</sub> )	Fall Time (Note 9)		1.0	1.8	3.0	ns				
t <sub>PZH</sub>	Enable Time (Z to Active High)	$R_{L} = 50\Omega, C_{L} = 5 \text{ pF},$			8	ns				
t <sub>PZL</sub>	Enable Time (Z to Active Low )	C <sub>D</sub> = 0.5 pF			8	ns				
t <sub>PLZ</sub>	Disable Time (Active Low to Z)	Figure 9 and Figure 10			8	ns				
t <sub>PHZ</sub>	Disable Time (Active High to Z)				8	ns				
t <sub>JIT</sub>	Random Jitter, RJ (Note 9)	100MHz clock pattern (Note 7)		2.5	5.5	psrms				
f <sub>MAX</sub>	Maximum Data Rate		200			Mbps				
	SPECIFICATION		-							
t <sub>PLH</sub>	Propagation Delay Low to High	C <sub>L</sub> = 15 pF	2.0	4.7	7.5	ns				
t <sub>PHL</sub>	Propagation Delay High to Low	Figures 11, 12 and Figure 13	2.0	5.3	7.5	ns				
t <sub>SKD1</sub> (t <sub>sk(p)</sub> )	Pulse Skew It <sub>PLHD</sub> – t <sub>PHLD</sub> I (Notes 5, 9)			0.6	1.9	ns				
t <sub>SKD3</sub>	Part-to-Part Skew (Notes 6, 9)				1.5	ns				
t <sub>TLH</sub> (t <sub>r</sub> )	Rise Time (Note 9)		0.5	1.2	3.0	ns				
t <sub>THL</sub> (t <sub>f</sub> )	Fall Time (Note 9)		0.5	1.2	3.0	ns				
t <sub>PZH</sub>	Enable Time (Z to Active High)	$R_{L} = 500\Omega, C_{L} = 15 \text{ pF}$			10	ns				
t <sub>PZL</sub>	Enable Time (Z to Active Low)	Figure 14 and Figure 15			10	ns				
t <sub>PLZ</sub>	Disable Time (Active Low to Z)				10	ns				
t <sub>PHZ</sub>	Disable Time (Active High to Z)				10	ns				
f <sub>MAX</sub>	Maximum Data Rate		200			Mbps				

Note 1: "Absolute Maximum Ratings" are those beyond which the safety of the device cannot be guaranteed. They are not meant to imply that the device should be operated at these limits. The tables of "Electrical Characteristics" provide conditions for actual device operation.

Note 2: All currents into device pins are positive; all currents out of device pins are negative. All voltages are referenced to device ground unless otherwise specified.

Note 3: All typicals are given for  $V_{CC}$  = 3.3V and  $T_A$  = 25°C.

Note 4: The algebraic convention, in which the least positive (most negative) limit is designated as minimum, is used in this datasheet.

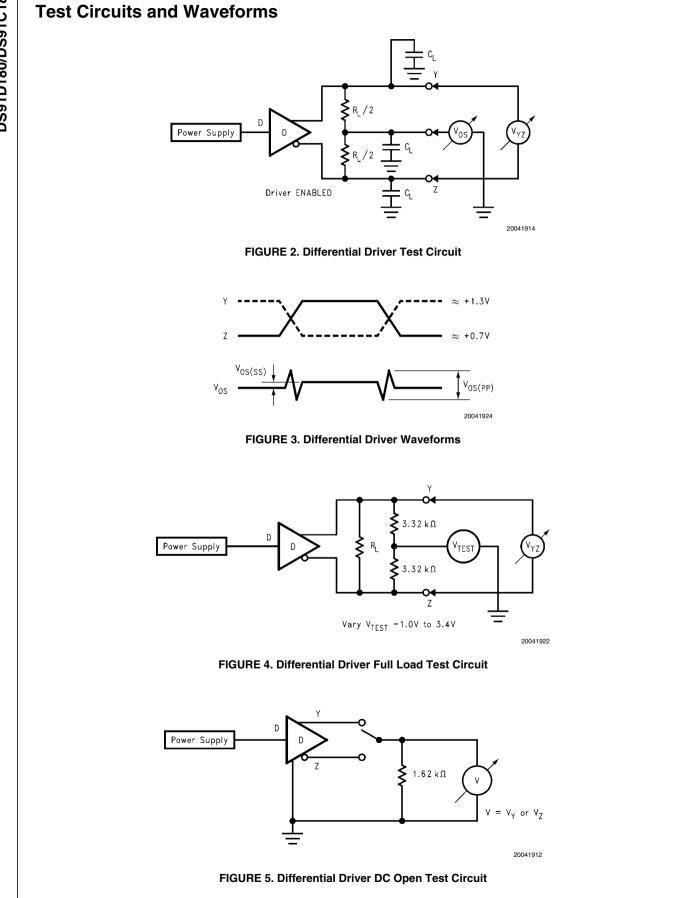
Note 5: t<sub>SKD1</sub>, |t<sub>PLHD</sub> - t<sub>PHLD</sub>|, is the magnitude difference in differential propagation delay time between the positive going edge and the negative going edge of the same channel.

Note 6:  $t_{SKD3}$ , Part-to-Part Skew, is defined as the difference between the minimum and maximum specified differential propagation delays. This specification applies to devices at the same  $V_{CC}$  and within 5°C of each other within the operating temperature range.

Note 7: Stimulus and fixture jitter has been subtracted.

Note 8:  $\mathrm{C}_{\mathrm{L}}$  includes fixture capacitance and  $\mathrm{C}_{\mathrm{D}}$  includes probe capacitance.

Note 9: Not production tested. Guaranteed by a statistical analysis on a sample basis at the time of characterization.



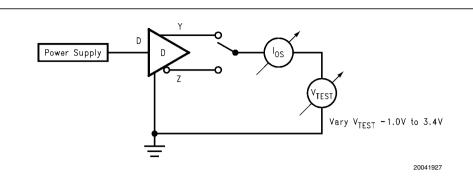


FIGURE 6. Differential Driver Short-Circuit Test Circuit

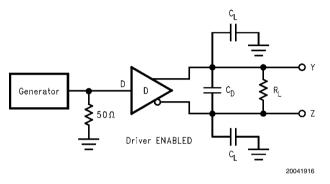


FIGURE 7. Driver Propagation Delay and Transition Time Test Circuit

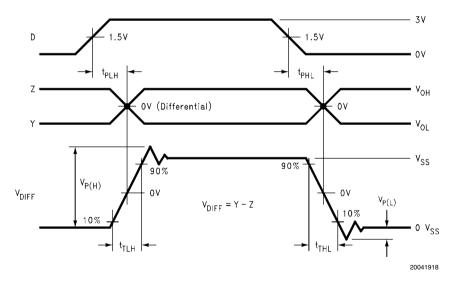
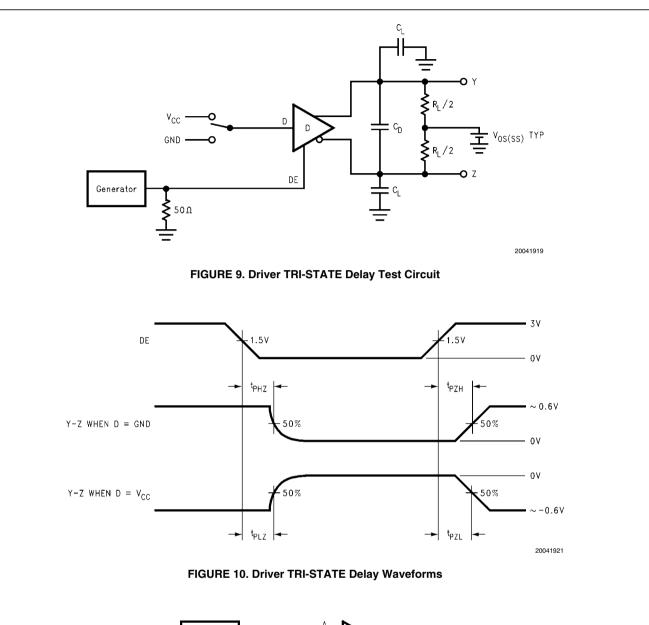


FIGURE 8. Driver Propagation Delays and Transition Time Waveforms





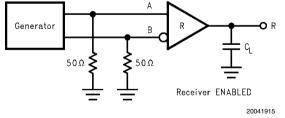


FIGURE 11. Receiver Propagation Delay and Transition Time Test Circuit



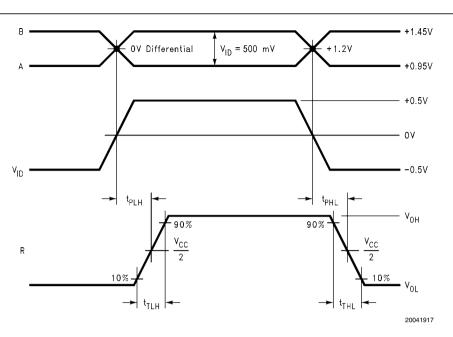
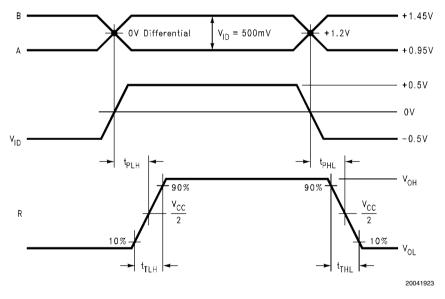
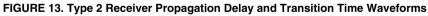
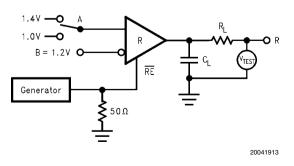


FIGURE 12. Type 1 Receiver Propagation Delay and Transition Time Waveforms











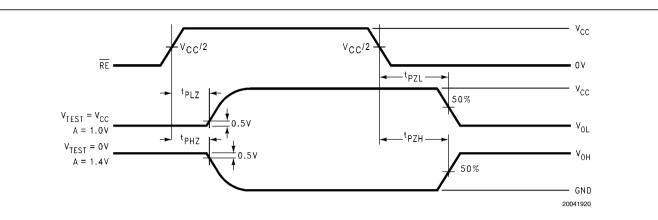


FIGURE 15. Receiver TRI-STATE Delay Waveforms

### **Function Tables**

#### DS91D180/DS91C180 Transmitting

Inp	uts	Outputs			
DE	D	Z	Y		
2.0V	2.0V	L	н		
2.0V	0.8V	н	L		
0.8V	Х	Z	Z		

X - Don't care condition Z - High impedance state

DS91D180 Receiving

5				
lı lı	Output			
RE	A – B	R		
0.8V	≥ +0.05V	Н		
0.8V	≤ -0.05V	L		
0.8V	0V	Х		
2.0V	Х	Z		

lı	nputs	Output
RE	A – B	R
0.8V	≥ +0.15V	Н
0.8V	≤ +0.05V	L
0.8V	0V	L
2.0V	Х	Z

X - Don't care condition Z - High impedance state

#### X — Don't care condition Z — High impedance state

#### DS91D180 Receiver Input Threshold Test Voltages

Applied Voltages		Resulting Differential Input Voltage	Resulting Common-Mode Input Voltage	Receiver Output
V <sub>IA</sub>	V <sub>IB</sub>	V <sub>ID</sub>	V <sub>IC</sub>	R
2.400V	0.000V	2.400V	1.200V	Н
0.000V	2.400V	-2.400V	1.200V	L
3.800V	3.750V	0.050V	3.775V	Н
3.750V	3.800V	-0.050V	3.775V	L
-1.400V	-1.350V	-0.050V	-1.375V	Н
-1.350V	-1.400V	0.050V	-1.375V	L

H — High Level L — Low Level

Output state assumes that the receiver is enabled ( $\overline{RE} = L$ )

#### DS91C180 Receiver Input Threshold Test Voltages

Applied Voltages		Resulting Differential Input Voltage	Resulting Common-Mode Input Voltage	Receiver Output	
VIA	V <sub>IB</sub>	V <sub>ID</sub>	V <sub>IC</sub>	R	
2.400V	0.000V	2.400V	1.200V	Н	
0.000V	2.400V	-2.400V	1.200V	L	
3.800V	3.650V	0.150V	3.725V	н	
3.800V	3.750V	0.050V	3.775V	L	
-1.250V	-1.400V	0.150V	-1.325V	н	
-1.350V	-1.400V	0.050V	-1.375V	L	

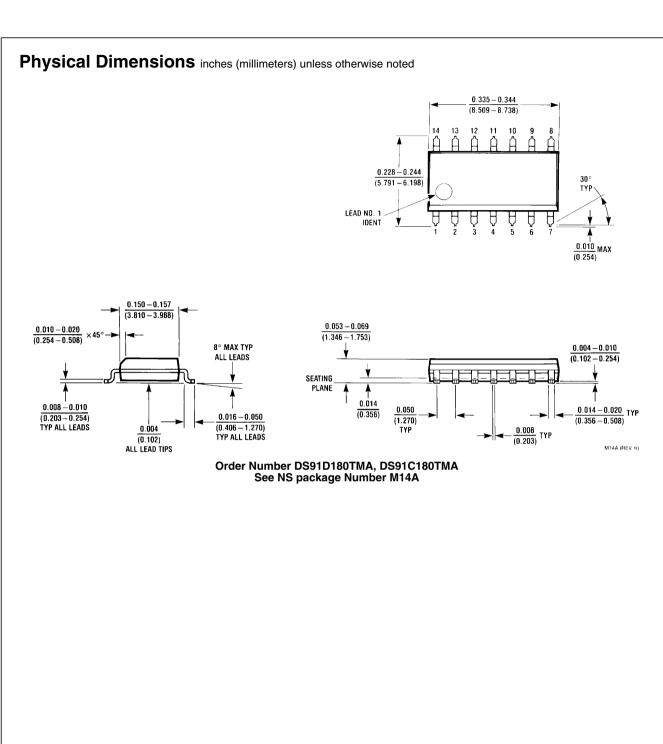
H — High Level L — Low Level

Output state assumes that the receiver is enabled ( $\overline{RE} = L$ )

# **Pin Descriptions**

Pin No.	Name	Description
1, 8	NC	No connect.
2	R	Receiver output pin
3	RE	Receiver enable pin: When $\overline{RE}$ is high, the receiver is disabled. When $\overline{RE}$ is low or open, the receiver is enabled.
4	DE	Driver enable pin: When DE is low, the driver is disabled. When DE is high, the driver is enabled.
5	D	Driver input pin
6, 7	GND	Ground pin
9	Y	Non-inverting driver output pin
10	Z	Inverting driver output pin
11	В	Inverting receiver input pin
12	A	Non-inverting receiver input pin
13, 14	V <sub>CC</sub>	Power supply pin, $+3.3V \pm 0.3V$





# Notes

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Ethernet	www.national.com/ethernet	Packaging	www.national.com/packaging
Interface	www.national.com/interface	Quality and Reliability	www.national.com/quality
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